



Product Change Notification / GBNG-190FUL850

Date:

24-Jun-2021

Product Category:

8-bit Microcontrollers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4409.001 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for Atmel AT80C51RD2-RLTUM and AT80C51RD2-RLRUM catalog part numbers (CPN) available in 44L LQFP (10x10x1.4mm) package using 236x236 mils lead frame paddle size at ANAP assembly site.

Affected CPNs:

[GBNG-190FUL850_Affected_CPN_06242021.pdf](#)

[GBNG-190FUL850_Affected_CPN_06242021.csv](#)

Notification Text:

PCN Status:Final notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for Atmel AT80C51RD2-RLTUM and AT80C51RD2-RLRUM catalog part numbers (CPN) available in 44L LQFP (10x10x1.4mm) package using 236x236 mils lead frame paddle size at ANAP assembly site.

Pre Change:

Using palladium coated copper (PdCu) bond wire material and 177x177 mils lead frame paddle size.

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire and 236x236 mils lead frame paddle size.

Pre and Post Change Summary:

		Pre Change	Post Change
Assembly Site		Amkor Technology Philippine (P1/P2), INC. / (ANAP)	Amkor Technology Philippine (P1/P2), INC. / (ANAP)
Wire material		PdCu	CuPdAu
Die attach material		3230	3230
Molding compound material		G700Y	G700Y
Lead frame	Material	C194	C194
	Paddle size	177x177 mils	236x236 mils
	Design	Please see attached pre and post change comparison	

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) bond wire.

Change Implementation Status:

In Progress

Estimated First Ship Date:

June 30, 2021 (date code: 2127)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	November 2020					-->	June 2021				
	Workweek	45	46	47	48		49	23	24	25	26
Initial PCN Issue Date				X							
Final PCN Issue Date										X	
Qual Report Availability										X	
Estimated Implementation Date											X

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

November 23, 2020: Issued initial notification.

June 24, 2021: Issued final notification. Attached is the qualification report. Provided estimated first ship date to be on June 30, 2021.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_GBNG-190FUL850_Pre_and_Post_Change_Summary.pdf](#)

[PCN_GBNG-190FUL850_Qual_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

AT80C51RD2-RLTUM

AT80C51RD2-RLRUM